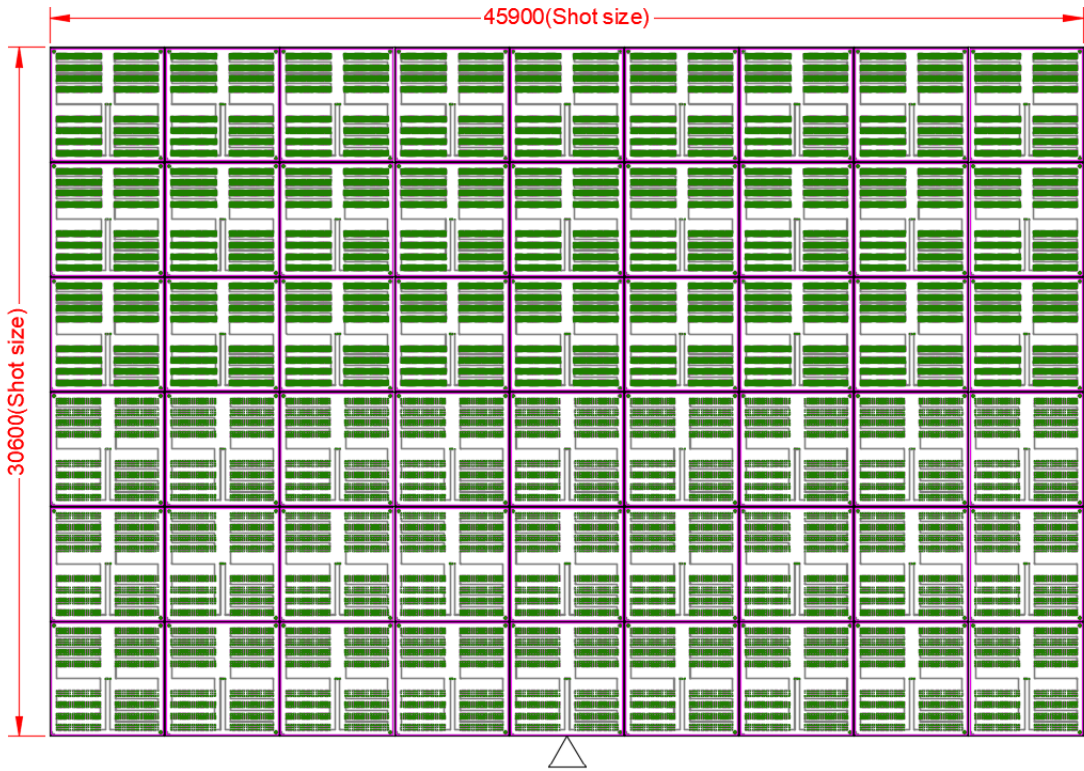


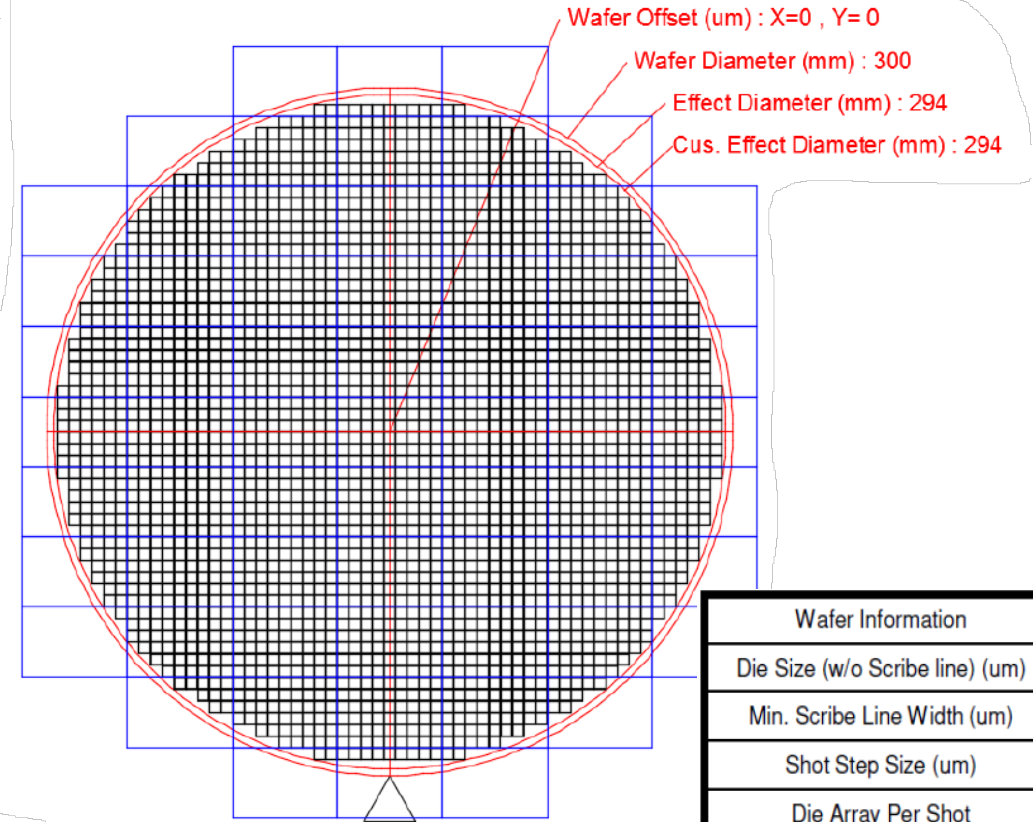
Structure

	Layer	Material	Thickness (um)	Min. Pad Size (um)	Remark
Chip Information	Wafer	Si oxide	700	--	
Design Information	Seed	Ti / Cu	0.1 / 0.2	Ø43	
	RDL-1	Cu	3		
	PI-1	BM-302H	5	Ø20	
	Seed	Ti / Cu	0.1 / 0.5	Ø35	Pitch:50(Min.)
	CPB	Cu / Ni / SnAg	32 / 3 /17	Ø35	
		Total	52		

All Layer



Shot Map



Wafer Information	X	Y
Die Size (w/o Scribe line) (um)	5000	5000
Min. Scribe Line Width (um)	100	100
Shot Step Size (um)	45900	30600
Die Array Per Shot	9	6
Wafer Offset(um)	0	0
		Customer
Gross Die	2500	--
Wafer Edge Exclusion (mm)	3	--
Shot Count (EA)	65	--
Wafer Foundry / Fab	--	
Wafer Tech Node (nm)	--	
Wafer Size (mm)	300	
Wafer Thickness (um)	700	
CP Testing	No	